## General Description

The SY21305A high efficiency synchronous stepup regulator operates using adaptive constant offtime and current mode control, and can deliver 15A current over a wide input voltage range from 3 V to 16 V . It integrates switches with low Rds(on) to minimize conduction loss.

The SY21305A features cycle-by-cycle peak current limit, output short-circuit protection, and true shutdown. It also provides enable control and power-good indicator for system sequence control. The programmable pseudoconstant frequency reduces output voltage ripple and permits smaller external capacitors and inductor.
The SY21305A is available in a compact QFN4×418 package.

## Features

- 3 V to 16 V Input Voltage Range
- Up to 15A Output Current
- Programmable Output Current Limit
- Low Ros(on) for Internal N-Channel MOSFET: $9 \mathrm{~m} \Omega$ Main, $12 \mathrm{~m} \Omega$ Rectifier, $12 \mathrm{~m} \Omega$ Disconnection FET
- Programmable Pseudoconstant Frequency
- Enable Control
- Input Voltage UVLO
- Output Overvoltage Protection
- Overtemperature Protection
- Output Short-Circuit Protection
- True Shutdown Function
- RoHS-Compliant and Halogen-Free
- Compact QFN4mm $\times 4 \mathrm{~mm}-18$ Package


## Applications

- Power Bank
- High Power Application


## Typical Application



Figure 1. Typical Application Circuit


Figure 2. Efficiency vs. Output Current

## Pinout (top view)



## Pin Description

| Pin Number | Pin Name | Pin Description |
| :---: | :---: | :---: |
| 1,9 | OUT | Boost converter output pin. |
| 2,8 | BD | Connect to the drain of the internal disconnect FET with at least a $4.7 \mu \mathrm{~F}$ ceramic capacitor to PGND. |
| 3,4,5 | PGND | Power ground pin. |
| 6,7 | LX | Inductor node. Connect an inductor from the power input to the LX pin. |
| 10 | BS | Bootstrap pin. Supply for rectifier FET's gate driver. Connect a $0.1 \mu \mathrm{~F}$ ceramic capacitor between the BS pin and the LX pin. |
| 11 | EN | Enable control. Pull high to enable the regulator; pull low to disable the regulator. Do not leave floating. |
| 12 | PG | Power-good indicator. Open-drain output pulled low when the output is less than $90 \%$ of regulation voltage, high impendence otherwise. |
| 13 | SVIN | Device power supply pin. Decouple this pin to the SGND pin with a $2.2 \mu \mathrm{~F}$ ceramic capacitor. |
| 14 | SGND | Signal ground pin. |
| 15 | ILIM | Output current limit program pin. Connect a resistor Rlim from this pin to SGND to program the output current limitation threshold. $\operatorname{LLIM}(\mathrm{A})=30(\mathrm{~V}) / \operatorname{RLIM}^{(\mathrm{k} \Omega)}$ |
| 16 | FS | Switching frequency setting pin. Connect a resistor from this pin to ground to program the switching frequency. $\operatorname{fsw}(\mathrm{kHz})=1.4 \times 10^{6} / \operatorname{RFS}(\Omega)^{0.645}$ |
| 17 | COMP | Loop compensation pin. Connect an RC network between this pin and ground to stabilize the control loop. |
| 18 | FB | Feedback pin. Connect to the center of the resistor voltage divider to program the output voltage. <br> Vout $=1 \mathrm{~V} \times\left(\mathrm{R}_{1} / \mathrm{R}_{2}+1\right)$ |

## $Y$

## Block Diagram



## Absolute Maximum Ratings

| Parameter (Note1) | Min | Max | Unit |
| :--- | :---: | :---: | :---: |
| SVIN, LX, EN, ILIM, OUT, BD, BS, FS, PG, COMP | -0.3 | 18 | V |
| FB, BS-LX | -0.3 | 4 |  |
| LX, 10ns Duration | -3.5 | 260 |  |
| Lead Temperature (Soldering, 10 sec.) |  | 260 |  |
| Junction Temperature, Operating | C |  |  |
| Storage Temperature |  | 150 |  |

## Thermal Information

| Parameter (Note2) | Typ | Unit |
| :--- | :---: | :---: |
| $\theta_{\text {JA }}$ Junction-to-Ambient Thermal Resistance | 30 | ${ }^{\circ} \mathrm{C} / \mathrm{W}$ |
| $\theta_{\mathrm{Jc}}$ Junction-to-Case Thermal Resistance | 3.2 |  |
| PD Power Dissipation $\mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$ | 3.4 | W |

## Recommended Operating Conditions

| Parameter (Note3) | Min | Max | Unit |
| :--- | :---: | :---: | :---: |
| SVIN | 3 | 16 | V |
| Junction Temperature, Operating | -40 | 125 | ${ }^{\circ} \mathrm{C}$ |
| Ambient Temperature | -40 | 85 |  |

## Electrical Characteristics

( $\mathrm{V}_{\text {IN }}=5 \mathrm{~V}$, $\mathrm{V}_{\text {OUT }}=12 \mathrm{~V}$, lout $=100 \mathrm{~mA}, \mathrm{~T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$ unless otherwise specified)

| Parameter | Symbol | Test Conditions | Min | Typ | Max | Unit |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| Input Voltage Range | VIN |  | 3 |  | 16 | V |
| Output Voltage Range | Vout |  | $\mathrm{V}_{1 \times 1} \times 1.1$ |  | 16 | V |
| Output OVP Threshold | $\mathrm{V}_{\text {FB_OVP }}$ | $V_{\text {FB }}$ Rising | 110\% | 115\% | 120\% | $V_{\text {ReF }}$ |
| Quiescent Current | lQ | Vout $=13 \mathrm{~V}$ |  |  | 230 | $\mu \mathrm{A}$ |
| Shutdown Current | ISHDN | $\mathrm{EN}=0$ |  |  | 5 | $\mu \mathrm{A}$ |
| FB Leakage Current | $\mathrm{I}_{\text {FB }}$ |  | -50 |  | 50 | nA |
| Main N-FET Ron | RDS(ON)_M |  |  | 9 |  | $\mathrm{m} \Omega$ |
| Rectified N-FET Ron | RDS(ON)_R |  |  | 12 |  | $\mathrm{m} \Omega$ |
| Disconnect N-FET Ron | RDs(ON)_D |  |  | 12 |  | $\mathrm{m} \Omega$ |
| Main N-FET Current Limit | ILIM,PEAK |  | 15 |  | 20 | A |
| Switching Frequency | fsw | RFs $=390 \mathrm{k} \Omega$ |  | 345 |  | kHz |
| Switching Frequency Programmable Range |  |  | 250 |  | 1000 | kHz |
| Feedback Reference Voltage | $V_{\text {REF }}$ |  | 0.985 | 1 | 1.015 | V |
| IN UVLO Rising Threshold | VIN,UVLO |  |  |  | 2.85 | V |
| UVLO Hysteresis | VHYs,UVLO |  |  | 0.2 |  | V |
| EN Rising Threshold | Venh |  | 1.5 |  |  | V |
| EN Falling Threshold | VenL |  |  |  | 0.4 | V |
| Output Current Limit | LIIM | RLIM $=15 \mathrm{k} \Omega$ |  | 1 |  | A |
| Output Current Limit |  | Vout $<=5 \mathrm{~V}$ | 1 |  | 5 | A |
| Programmable Range | lıIM,OUT | Vout $>5 \mathrm{~V}$ | 1 |  | 4 | A |
| Minimum On-Time | ton,min |  |  | 100 |  | ns |
| Minimum Off-Time | toff,MIN |  |  | 120 |  | ns |
| Error Amplifier Transconductance | $\mathrm{gm}_{\text {m }}$ |  |  | 100 |  | $\mu \mathrm{S}$ |
| Current Sense Gain | Ri |  |  | 75 |  | $\mathrm{m} \Omega$ |
| Thermal Shutdown Temperature | Tsd |  |  | 150 |  | ${ }^{\circ} \mathrm{C}$ |
| Thermal Shutdown Hysteresis | Thys |  |  | 20 |  | ${ }^{\circ} \mathrm{C}$ |

Note 1: Stresses beyond the "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only. Functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specification is not implied. Exposure to absolute maximum rating conditions may affect device reliability.
Note 2: $\theta_{\mathrm{JA}}$ is measured in the natural convection at $\mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C}$ on a two-layer Silergy Evaluation Board.
Note 3: The device is not guaranteed to function outside its operating conditions.

## SILERGY

## Typical Performance Characteristics

( $\mathrm{T}_{\mathrm{A}}=25^{\circ} \mathrm{C}, \mathrm{V}_{\text {OUt }}=12 \mathrm{~V}, \mathrm{f}_{\mathrm{Sw}}=350 \mathrm{kHz}, \mathrm{L}=2.2 \mu \mathrm{H}, \mathrm{C}_{\text {out }}=44 \mu \mathrm{~F}$, unless otherwise specified.)



Time ( $400 \mu \mathrm{~s} / \mathrm{div}$ )


Time ( $800 \mu \mathrm{~s} / \mathrm{div}$ )


Time (4ms/div)


Time (4ms/div)


Time (4ms/div)


Time (20ms/div)


## Detailed Description

The SY21305A high efficiency synchronous step-up regulator operates using adaptive constant off-time and current mode control, and can deliver 15A current over a wide input voltage range from 4.5 V to 30 V . It integrates switches with low Ros(on) to minimize conduction loss.
The SY21305A features cycle-by-cycle peak current limit, output short-circuit protection, and true shutdown. It also provides enable control and power-good indicator for system sequence control. The programmable pseudoconstant frequency reduces output voltage ripple and permits smaller external capacitors and inductor.

## Enable Operation

Driving the EN pin high ( $>1.5 \mathrm{~V}$ ) enables normal operation. Driving the EN pin low ( $<0.4 \mathrm{~V}$ ) will shut down the device. During shutdown mode, the SY21305A shutdown current drops to less than $5 \mu \mathrm{~A}$.

## Switching Frequency

The switching frequency of the SY21305A in CCM (continuous conduction mode) can be programmed by adjusting an external resistor RFs connected to FS pin:

$$
\mathrm{fsw}_{\mathrm{sw}}(\mathrm{kHz})=1.4 \times 10^{6} / \operatorname{RFs}(\Omega)^{0.645}
$$

Under light load conditions, the SY21305A linearly folds back the frequency, to maintain high efficiency.


Figure 3. fsw vs RFs

## Power-Good Indicator

PG is an open-drain output pin. This pin will be pulled to ground if the output voltage is lower than $90 \%$ of the regulation voltage. Otherwise, this pin will go to a high impedance state.

## Loop Compensation

The SY21305A incorporates constant off-time current mode control with two feedback loops:

- The inner loop (current loop) does not require any external compensation component.
- The outer loop (voltage loop) is compensated with external components.
In most applications, a Type 2 or Type 2a compensation network, as shown in Figure 3, can be used to stabilize the voltage loop. Type 2 is most widely used, and it works fine for power stages lagging down to $-90^{\circ}$ and where the boost brought by the output capacitor ESR must be canceled. Type 2a is used where the output capacitor ESR effect can be neglected.


Figure 4. Compensation networks
Follow the steps below to calculate the value of external components for voltage loop compensation.

1. Select the crossover frequency fc of the closed loop. For the tradeoff between stability and transient response of the system, the recommended crossover frequency is the minimum value of $1 / 5$ of the right-half-plane zero (frhez) and $1 / 10$ of the switching frequency. The system has faster response at higher crossover frequency.

$$
f_{\text {RHPZ }}=\frac{\left(1-D_{M A X}\right)^{2} \times V_{\text {OUT }}}{2 \pi \times L \times I_{\text {OUT }}}
$$

2. Select an Rz value of the R-C series combination connected to the COMP pin:

$$
R_{Z}=\frac{V_{\text {OUT }}}{g_{M} \times G_{f c} \times V_{R E F}}
$$

where $g_{m}$ is the error amplifier transconductance, which is typically $50 \mu \mathrm{~S}$; $\mathrm{G}_{\mathrm{tc}}$ is the gain of the power stage at crossover frequency.

$$
G_{f c}=\frac{1-D_{M A X}}{2 \pi \times f_{c} \times C_{O U T} \times R_{i}}
$$

where $R_{i}$ is the current-sense resistance, which is typically $170 \mathrm{~m} \Omega$.
3. Select a Cz value of the $\mathrm{R}-\mathrm{C}$ series combination connected to the COMP pin. The compensation zero decides the phase margin at the crossover frequency.
Place a compensation zero at or before the dominant pole of $R_{L}$ and Co. $R_{L}$ is the load resistance, which equals Vout/lout.

$$
C_{Z}=\frac{V_{\text {OUT }} \times C_{\text {OUT }}}{I_{\text {OUT }} \times R_{Z}}
$$

4. A high frequency pole is recommended to attenuate the high frequency noise. Place this pole to cancel the ESR zero of Cout.

$$
\mathrm{C}_{\mathrm{P}}=\frac{\mathrm{R}_{\mathrm{ESR}} \times \mathrm{C}_{\mathrm{O}}}{\mathrm{R}_{\mathrm{Z}}}
$$

## Fault Protection Modes

## Output Current Limit

There are two feedback loops inside the regulator. When the voltage on ILIM pin reaches the 1V threshold, the current feedback loop will take over and regulate the output DC current to the target value.

$$
\operatorname{LІмм}(\mathrm{A})=15(\mathrm{~V}) / \operatorname{RLIM}(\mathrm{k} \Omega)
$$



Figure 5. LIMIT vs RLIMIT

## Short-Circuit Protection

The SY21305A features hiccup mode short-circuit protection, which is triggered if the device is operated in current limit continuously and Vout drops below 2V. The device will shut down for approximately 12 ms , and then restart with a complete soft-start cycle that is approximately 2 ms . If the short-circuit condition remains, the 'hiccup' cycle of shutdown and restart will continue indefinitely.

## Overtemperature Protection (OTP)

The SY21305A includes overtemperature protection (OTP) circuitry to prevent overheating due to excessive power dissipation. This will shut down switching operation when the junction temperature exceeds $150^{\circ} \mathrm{C}$. Once the junction temperature cools down by approximately $15^{\circ} \mathrm{C}$, the device will resume normal operation after a complete soft-start cycle. For continuous operation, provide adequate cooling so that the junction temperature does not exceed the OTP threshold.

## Application Information

The following paragraphs describe the selection process for the feedback resistor divider (R1 and R2), output current limit resistor RLIM, switching frequency program resistor RFS, input capacitor $\mathrm{C}_{\mathrm{IN}}$, output capacitors $\mathrm{C}_{\mathrm{BD}}$ and $\mathrm{C}_{\text {out, }}$ boost inductor L , and external bootstrap capacitor.

## Feedback Resistor Divider R1 and R2

Choose R1 and R2 to program the proper output voltage. Choose large resistance values between $10 \mathrm{k} \Omega$ and $1 \mathrm{M} \Omega$ for both R1 and R2 to minimize power consumption under light loads. If a value is chosen for R1, then R2 can be calculated as:

$$
R 2=\frac{0.6 \mathrm{~V}}{V_{\text {OUT }}-0.6 \mathrm{~V}} R 1
$$



## Input Capacitor $\mathrm{C}_{\text {IN }}$

Input filter capacitors reduce the ripple voltage on the input, filter the switched current drawn from the input supply, and reduce potential EMI. When selecting an input capacitor, select a voltage rating at least $20 \%$ greater than the maximum voltage of the input supply and a temperature rating higher than the system requirements. X5R series ceramic capacitors are most often selected due to their
small size, low cost, surge-current capability, and high RMS current ratings over a wide temperature and voltage range. However, systems that are powered by a wall adapter or other long and therefore inductive cabling may be susceptible to significant inductive ringing at the input to the device. In these cases, consider adding some bulk capacitance like electrolytic, tantalum, or polymer type capacitors. Using a combination of bulk capacitors (to reduce overshoot or ringing) in parallel with ceramic capacitors (to meet the RMS current requirements) is helpful in these cases.

Consider the RMS current rating of the input capacitor, paralleling additional capacitors if required to meet the calculated RMS ripple current.

$$
I_{C I N \_R M S}=\frac{V_{I N} \times\left(V_{O U T}-V_{I N}\right)}{\sqrt[2]{3} \times L \times f_{S W} \times V_{O U T}}
$$

For the best performance, select a typical X5R or better grade low ESR $10 \mu \mathrm{~F}$ ceramic capacitor and place it as close as possible to the $\mathrm{V}_{\mathrm{IN}}$ and PGND pins. Minimize the loop area formed by $\mathrm{Cin}_{\mathrm{N}}, \mathrm{V}_{\mathrm{N}}$, and the PGND pin.
The SVIN capacitor must be placed as close as possible to the SVIN and SGND pins. Minimize the loop area formed by $\mathrm{CIN}_{\mathrm{N}}$ and the SVIN/SGND pins. In this case, a $2 \mu \mathrm{~F}$ low ESR ceramic capacitor is recommended.

## Boost Output Capacitor Cbd and Disconnection FET Output Capacitor Cout <br> The boost output capacitor $\mathrm{C}_{\mathrm{Bd}}$ and disconnection FET

 output capacitor Cout are selected to handle the output ripple noise requirements. Both steady state ripple and transient requirements must be considered when selecting these capacitors. For the best performance, it is recommended to use X5R or better grade ceramic capacitors with 25 V rating and more than $22 \mu \mathrm{~F}$ capacitance for both components.
## Boost Inductor L

Consider the following when choosing this inductor:

1) Choose the inductance to provide a ripple current that is approximately $40 \%$ of the maximum output current. The recommended inductance is calculated as:

$$
L=\left(\frac{V_{I N}}{V_{\text {OUT }}}\right)^{2} \frac{V_{\text {OUT }}-V_{I N}}{f_{S W} I_{\text {OUT,MAX }} \times 0.4}
$$

where fsw is the switching frequency and lout,max is the maximum load current.
The SY21305A has high tolerance for ripple current amplitude variation. As a result, the final choice of inductance can vary slightly from the calculated value with no significant performance impact.
2) The inductor's saturation current rating must be greater than the peak inductor current under full load:

$$
I_{S A T, M I N}=\left(\frac{V_{\text {OUT }}}{V_{I N}}\right) \times I_{\text {OUT }, M A X}+\frac{V_{I N}\left(V_{\text {OUT }}-V_{I N)}\right.}{2 \times f_{S W} \times L \times V_{\text {OUT }}}
$$

3) The DCR of the inductor and the core loss at the switching frequency must be low enough to achieve the desired efficiency requirement. Choose an inductor with DCR less than $10 \mathrm{~m} \Omega$ to achieve good overall efficiency.

## External Bootstrap Capacitor

This capacitor provides the gate driver voltage for the internal rectifier. A 100 nF low ESR ceramic capacitor connected between the BS pin and the LX pin is recommended.


## Application Schematic



## Design Specifications

| Input Voltage (V) | Output Voltage (V) | Output Current Limit (A) |
| :---: | :---: | :---: |
| $3-10$ | 12 | 2 |

## BOM List

| Reference Designator | Description | Part Number | Manufacturer |
| :---: | :---: | :---: | :---: |
| C1 | $220 \mu \mathrm{~F} / 35 \mathrm{~V}$, Electrolytic Cap |  |  |
| C2,C5,C6,C7 | $22 \mu \mathrm{~F} / 25 \mathrm{~V} 1206$ | C3216X5R1E226M | TDK |
| C4 | $2.2 \mu \mathrm{~F} / 25 \mathrm{~V} 1206$ | C3216X7R1E225K | TDK |
| C8 | $0.1 \mu \mathrm{~F} / 50 \mathrm{~V} / \mathrm{X} 7 \mathrm{R}, 0603$ | C1608X7R1H104K | TDK |
| C9 | $1 \mathrm{nF} / 50 \mathrm{~V} \mathrm{0603}$ |  |  |
| C10 | $22 \mathrm{pF} / 50 \mathrm{~V} 0603$ |  |  |
| C3 | SPARE |  |  |
| R1 | $110 \mathrm{k}, 1 \%, 0603$ |  |  |
| R2 | $10 \mathrm{k}, 1 \%, 0603$ |  |  |
| R3 | $100 \mathrm{k}, 1 \%, 0603$ |  |  |
| R5 | $1 \mathrm{M} \Omega, 1 \%, 0603$ |  |  |
| R6 | $5.1 \mathrm{k}, 1 \%, 0603$ |  | CYNTECH |
| R8 | $30 \mathrm{~K} \Omega, 1 \%, 0603$ |  | SILERGY |
| R9 | $10 \Omega, 1 \%, 0603$ |  |  |
| L1 | $390 \mathrm{~K} \Omega, 1 \%, 0603$ | PIMB104T-2R2MS |  |
| U1 | Inductor $2.2 \mu \mathrm{H} / 12 \mathrm{~A}$ |  |  |

## Recommend Components for Typical Applications

| $\mathbf{V}_{\text {out }}(\mathbf{V})$ | $\mathbf{R 1}(\mathbf{k} \boldsymbol{\Omega})$ | $\mathbf{R 2}(\mathbf{k} \boldsymbol{)}$ | $\mathbf{L}(\mu \mathrm{H})$ | Cout |
| :---: | :---: | :---: | :---: | :---: |
| 12 | 110 | 10 | 2.2 | $2 \times 22 \mu \mathrm{~F} / 25 \mathrm{~V} / \mathrm{X} 7 \mathrm{R}, 1206$ |
| 9 | 80.6 | 10 | 2.2 | $2 \times 22 \mu \mathrm{~F} / 25 \mathrm{~V} / \mathrm{X} 7 \mathrm{R}, 1206$ |
| 5 | 80.6 | 20 | 1 | $2 \times 22 \mu \mathrm{~F} / 25 \mathrm{~V} / \mathrm{X} 7 \mathrm{R}, 1206$ |

$\qquad$

## Layout Design

To achieve optimal design, follow these PCB layout considerations:

- Place $\mathrm{C}_{\mathrm{in}}, \mathrm{C}_{\mathrm{bd}}$, Cout, L, R1, and R2 close to the IC
- To achieve the best thermal and noise performance, maximize the PCB copper area connecting to the GND pin. A ground plane is highly recommended if board space allows.
- $\mathrm{C}_{\mathbb{I}}$ must be close to pins SVIN and SGND. Minimize the loop area formed by $\mathrm{C}_{\mathrm{BD}}, \mathrm{LX}$, and PGND.
- To reduce switching noise, minimize the PCB copper area connected to the LX pin.
- In order to reduce crosstalk, R1, R2, and the trace connected to the FB pin must not be adjacent to the LX net on the PCB layout.
- If the system chip interfacing with the EN pin has a high impedance state during shutdown mode, and the SVIN pin is connected directly to a power source such as a Li-ion battery, add a $1 \mathrm{M} \Omega$ pulldown resistor between the EN and GND pins to prevent noise from falsely triggering the regulator during shutdown mode.


Figure 6. Suggested PCB Layout

## QFN4×4-18 Package Outline and PCB Layout



Bottom view


Side view


Recommended PCB layout (reference only)

Note: All dimensions are in millimeters and exclude mold flash and metal burr.

## Taping and Reel Specification

## QFN4×4 taping orientation



Feeding direction $\longrightarrow$

## Carrier tape and reel specification for packages



| Package <br> types | Tape width <br> $(\mathrm{mm})$ | Pocket <br> pitch(mm) | Reel size <br> (Inch) | Trailer <br> length(mm) | Leader length <br> $(\mathrm{mm})$ | Qty per <br> reel |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| QFN $4 \times 4$ | 12 | 8 | $13^{\prime \prime}$ | 400 | 400 | 5000 |

Others: NA

## Revision History

The revision history provided is for informational purposes only and is believed to be accurate, however, not warranted. Please make sure that you have the latest revision.

| Date | Revision | Change |
| :--- | :--- | :--- |
| Apr.20, 2023 | Revision 1.0 | Language improvements for clarity. |
| Mar.05, 2019 | Revision 0.9E | Add Recommended PCB layout ( (Reference only) in Package Outline |
| Sep. 27, 2017 | Revision 0.9D | 1. Add "Error Amplifier Trans-conductance"\& "Current Sense Gain" in EC table; <br> 2. Correct the formula for Output Inductor L (page8); |
|  |  | 3. Add "Loop Compensation" in "Applications Information". |
| June 20, 2017 | Revision 0.9C | Add "Output Voltage Range" in EC table. |

## IMPORTANT NOTICE

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